

SOT2135-1

WLCSP103, wafer level chip scale package, 103 terminals,
0.33 mm pitch, 4.05 mm x 3.16 mm x 0.38 mm body

4 March 2022

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP103
Package type industry code	WLCSP103
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	20-08-2021
Manufacturer package code	98ASA01752D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.02	4.05	4.08	mm
package width	3.13	3.16	3.19	mm
package height	-	0.38	0.41	mm
nominal pitch	-	0.33	-	mm
actual quantity of termination	-	103	-	



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2 Package outline

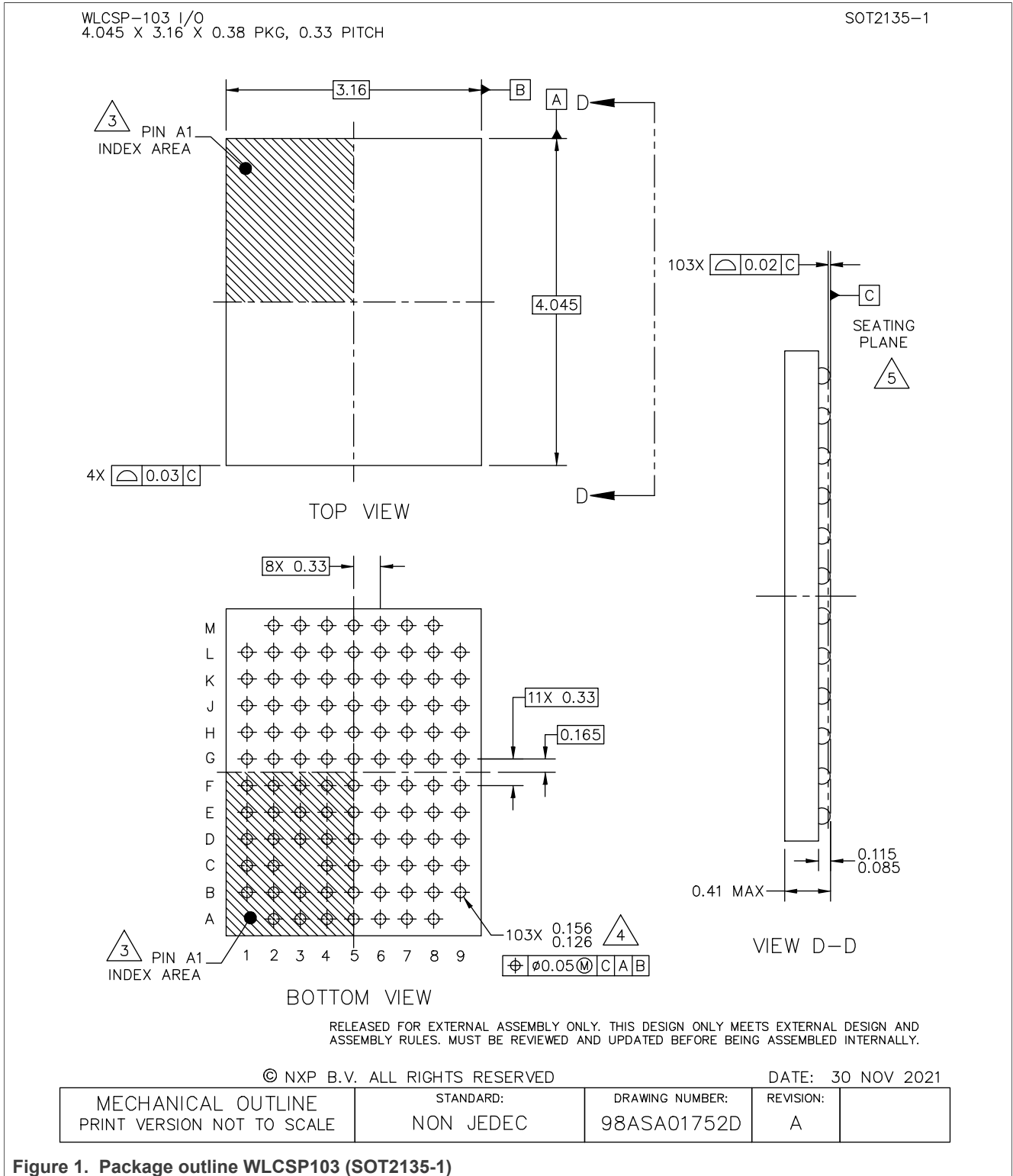
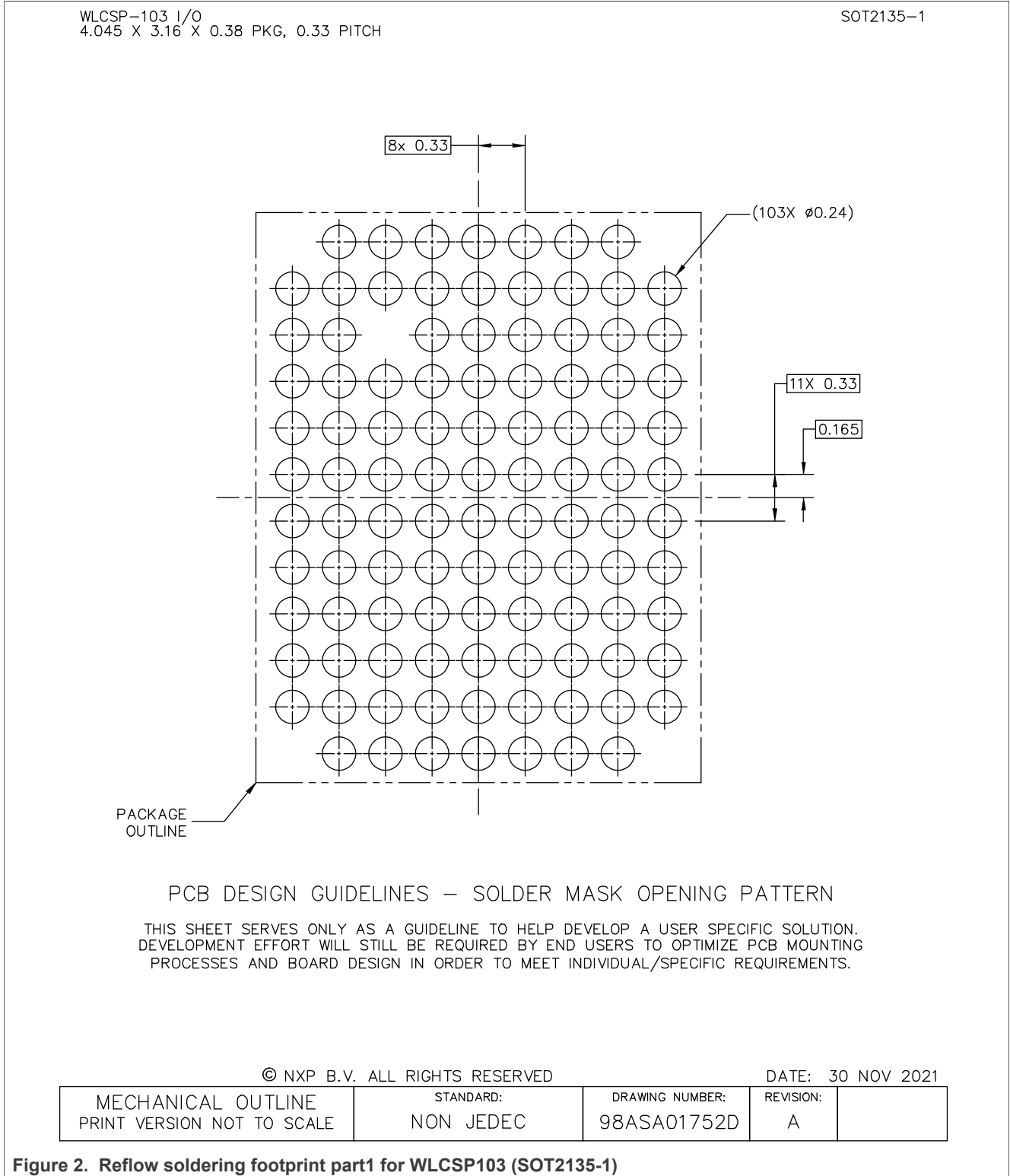


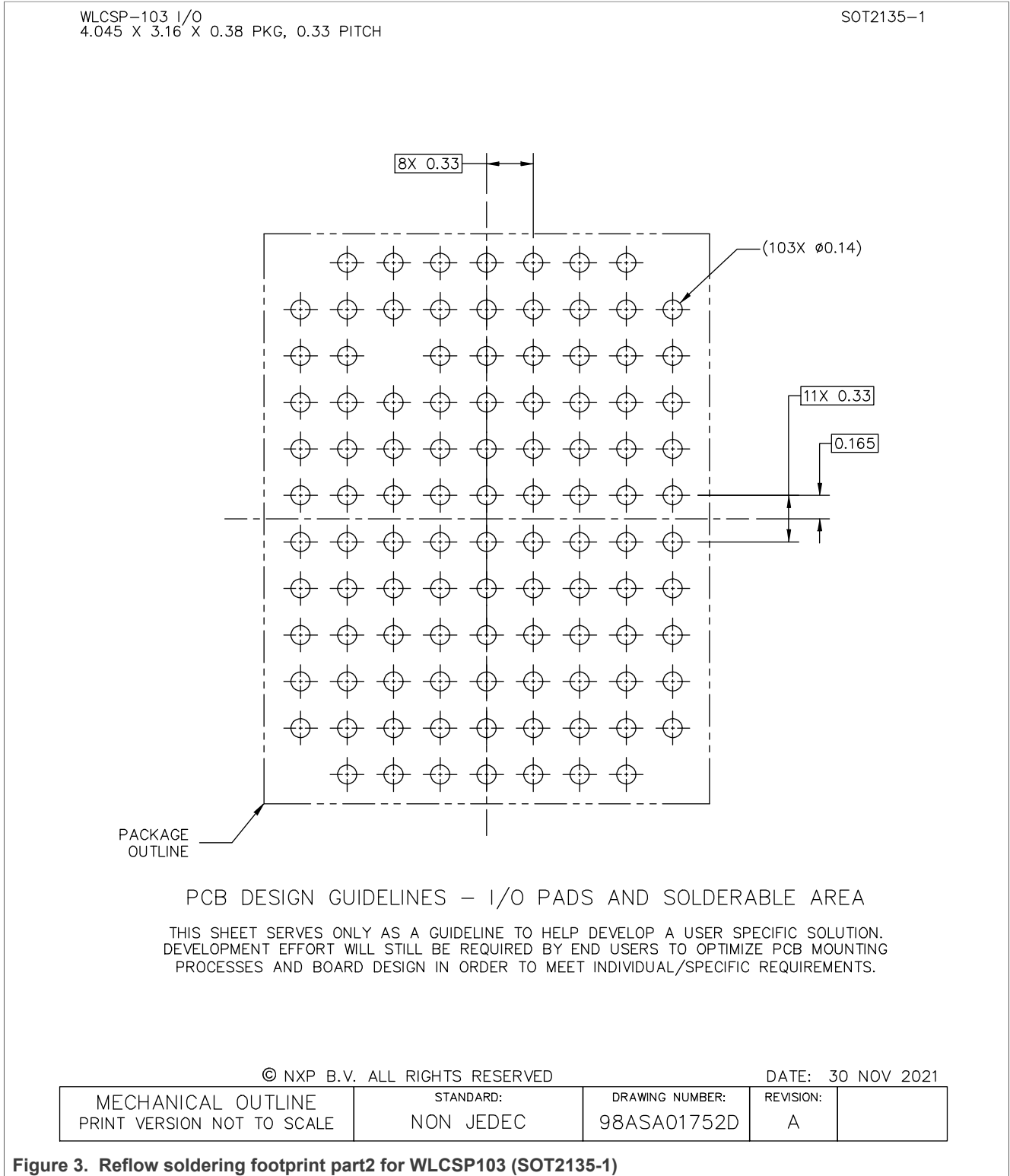
Figure 1. Package outline WLCSP103 (SOT2135-1)

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3 Soldering



WLCSP103, wafer level chip scale package, 103 terminals, 0.33 mm pitch, 4.05 mm x 3.16 mm x 0.38 mm body



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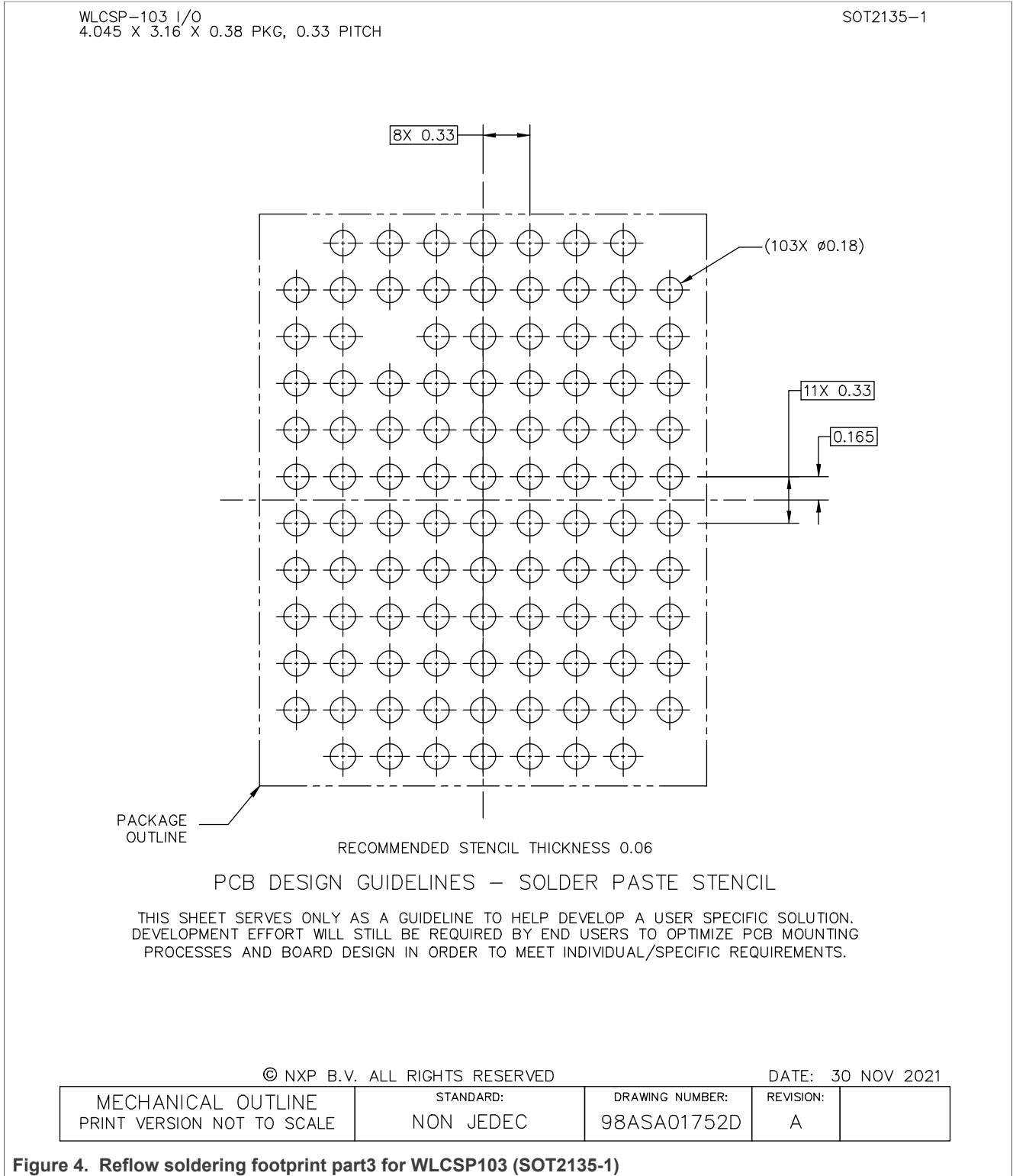


Figure 4. Reflow soldering footprint part3 for WLCSP103 (SOT2135-1)

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WLCSP-103 I/O
4.045 X 3.16 X 0.38 PKG, 0.33 PITCH

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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DATE: 30 NOV 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01752D	REVISION: A	
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Figure 5. Package outline note WLCSP103 (SOT2135-1)

4 Legal information

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body

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